IN THE CLAIMS

This listing of claims will replace all prior versions, and listings, of claims in the application:

Listing of Claims:

1. (Currently Amended) A method of fabricating a set of semiconducting nanowires having a desired wire diameter, the method comprising the steps-acts of:

providing a set of pre-fabricated semiconducting nanowires, at least one pre-fabricated semiconducting nanowire having a wire diameter larger than the desired wire diameter, and diameter;

reducing the wire diameter of the at least one pre-fabricated nanowire by etching, the etching being induced by electromagnetic radiation which is absorbed by the at least one pre-fabricated nanowire, nanowire;

selecting a minimum wavelength of the electromagnetic radiation being chosen such that the absorption of the at least one

pre-fabricated nanowire being is significantly reduced when the at least one pre-fabricated nanowire reaches the desired wire diameter diameter; and

stopping the electromagnetic radiation when continuing the electromagnetic radiation does not substantially change the desired wire diameter.

- 2.(Currently Amended) A The method as claimed in claim 1, wherein:
- a radiation source is used which emits the electromagnetic radiation inducing the etching and electromagnetic radiation having a wavelength shorter than the minimum wavelength, and

the electromagnetic radiation emitted by the radiation source is spectrally filtered for substantially reducing electromagnetic radiation having a wavelength shorter than the minimum wavelength.

3.(Currently Amended) A The method as claimed in claim 1, wherein prior to the step of reducing act, the wire diameter substantially all the pre-fabricated semiconducting nanowires have

a diameter larger than or equal to the desired wire diameter diameter.

- 4. (Currently Amended) A—The method as claimed in claim 1, wherein the light inducing the etch treatment is linearly polarized along an axis—axis.
- 5. (Currently Amended) A The method as claimed in claim 1, wherein the light inducing the etch treatment has a first component being linearly polarized along a first axis and a second component being linearly polarized along a second axis forming an angle larger than zero with the first axis axis.
- 6. (Currently Amended) A The method as claimed in claim 5, the first component has a first spectrum with a first minimum wavelength and the second component has a second spectrum with a second minimum wavelength different from the first minimum wavelength.

- 7. (Currently Amended) A—The method as claimed in claim 5, wherein the first component has a first intensity and the second component has a second intensity different from the first intensity.
- 8.(Currently Amended) A The method as claimed in claim 1, wherein the desired wire diameter comprises zero.
- 9. (Currently Amended) A The method as claimed in claim 8, wherein the light inducing etching of nanowires having a desired wire diameter of zero is linearly polarized.
- 10.(Currently Amended) A—The method as claimed in claim 1, wherein the pre-fabricated semiconducting nanowires are supported by a substrate substrate.
- 11.(Currently Amended) A_The method as claimed in claim 10, wherein the substrate comprises an electrical conductor, the prefabricated semiconducting nanowires being electrically conductively

connected to the electrical conductor conductor.

- 12. (Currently Amended) A The method as claimed in claim 10, wherein the substrate has a surface constituted by a first part supporting the pre-fabricated semiconducting nanowires and another a second part being free from the part at first part, at least the other second part being etch resistant.
- 13. (Currently Amended) A The method as claimed in claim 12, wherein the substrate comprises a first layer which is not etch resistant, and a second layer which is etch resistant, the second layer constituting the other second part of the surface surface.
- 14. (Currently Amended) A The method as claimed in claim 13, wherein the second layer is connected to the first layer by a chemical bond.
- 15. (Currently Amended) A The method as claimed in claim 13, wherein the second layer is composed of one or more materials

selected from alkyltriethoxysiloxane and alkyltrimethoxysiloxane.

16. (Currently Amended) A The method as claimed in claim 10, wherein the step of providing the pre-fabricated semiconducting nanowires act comprises the following sub-steps acts:

providing the substrate, a surface of the substrate being etchable, and

growing semiconducting nanowires on the surface of the substrate, the grown semiconducting nanowires being the prefabricated semiconducting nanowires,

and after the step of providing the pre-fabricated semiconducting nanowires act and prior to the step of reducing the wire diameter of the at least one pre-fabricated nanowire by etching the act, exposed surface of the substrate is covered by an etch resistant layer layer.

17. (Currently Amended) A—The method as claimed in claim 10, wherein the pre-fabricated semiconducting nanowires are distributed over the surface, a first part of the surface being irradiated by

light for inducing the etch treatment, pre-fabricated semiconducting nanowires in a second part of the surface being prevented from etching.

- 18.(Currently Amended) A—The method as claimed in claim 10, wherein the pre-fabricated semiconducting nanowires are distributed over the surface, a first part of the surface area being irradiated by a first light intensity, a second part of the surface free from the first part of the surface being irradiated by a second light intensity smaller than the first light intensity.
- 19.(Currently Amended) A—The method as claimed in claim 10, wherein the pre-fabricated semiconducting nanowires are distributed over the surface, a first part of the surface being irradiated by light having a first minimum wavelength, a second part of the surface being irradiated by light having a second minimum wavelength different from the first minimum wavelength.

Claims 20-29 (Canceled)

30.(New) The method of claim 1, further comprising the acts of:

doping a first part of the at least one pre-fabricated semiconducting nanowire to form a p-doped nanowire; and

doping a second part of the at least one pre-fabricated semiconducting nanowire to form a n-doped nanowire;

wherein the reducing act reduces a diameter of the p-doped nanowire to be smaller than a diameter of the n-doped nanowire so that the p-doped nanowire emits radiation of reduced wavelength as compared to a p-doped nanowire with an unreduced diameter, and the n-doped nanowire provides higher current as compared to an n-doped nanowire with a reduced diameter.